



1. The first group of variables, *demographics*, includes age, sex, and marital status. The second group, *education*, includes years of schooling, high school graduation, and college graduation. The third group, *employment*, includes employment status, occupation, and industry. The fourth group, *income*, includes household income and personal income. The fifth group, *housing*, includes home ownership, home value, and home age. The sixth group, *transportation*, includes car ownership and car age. The seventh group, *leisure*, includes leisure time and leisure activities. The eighth group, *health*, includes health status and health insurance. The ninth group, *social*, includes social network and social support. The tenth group, *psychological*, includes psychological well-being and psychological stress. The eleventh group, *environmental*, includes environmental quality and environmental concern. The twelfth group, *political*, includes political participation and political engagement. The thirteenth group, *economic*, includes economic satisfaction and economic confidence. The fourteenth group, *cultural*, includes cultural participation and cultural consumption. The fifteenth group, *religious*, includes religious participation and religious belief. The sixteenth group, *family*, includes family size and family structure. The seventeenth group, *community*, includes community involvement and community satisfaction. The eighteenth group, *national*, includes national identity and national pride. The nineteenth group, *international*, includes international travel and international experience. The twentieth group, *global*, includes global awareness and global responsibility.

Water-level package 1A

WTR - In the manufacture of semiconductor devices.

ADVANTAGE - Large test circuit area still being, or about to be, utilized with 1A,  
which is a high level of manufacturing efficiency and is implemented in a single water.

DESCRIPTION OF DRAWING - The drawing shows a diagram of the invention.

Water-level package 1A

Semiconductor water 11

Chip terminal region 12

Test chip terminal 1A

Non-test chip terminal 1B

External connection terminal 14

Redistribution trace 15

Test terminal 17

ABSTRACT-INT-N : 11-111-111

EQUIVALENT-ABSTRACT:

WTR - A water-level package 1A including a semiconductor water 11 with  
at least one chip terminal region 12 each including a semiconductor chip  
direct with test and non-test chip terminals 1A, 1B, at least one external  
connection terminal 14, a redistribution trace 15, test terminal 17 and  
insulation material. One end of the test terminal is connected to test chip terminal  
and the other end of the test terminal is the test terminal of the chip  
terminal region.

DETAILS AND FIGURE - An embodiment of the invention is shown in







### ***Double Patenting***

3 In claim 1 of the instant application the word "semiconductor" on line 2 is added to the claim. However, the IC die (i.e. integrated circuit die) of U.S. Patent 6,316,824 is a semiconductor die. In claim 1 of the instant application the phrase "at least one bond pad thereon" on line 2 was replaced with "a plurality of bond pads thereon" in U.S. Patent No. 6,316,824. However, at least one bond pad is present in a plurality of bond pads. In claim 1, of the instant application the phrase **for attachment in one of a conventional die attach to lead frame connect process and a LOC connect process** is added to the claim. However, a connector (i.e. bonding wire) is an attachment means for a conventional die to a lead frame. In claim 3, of the instant application the word "semiconductor" on line 2 is added to the claim. However, the IC die (i.e. integrated circuit die) of U.S. Patent 6,316,824 is a semiconductor die. In claim 3 of the instant application the phrase "at least one bond pad thereon" on line 2 was replaced with "a plurality of bond pads thereon" in U.S. Patent No. 6,316,824. However, at least one bond pad is present in a plurality of bond pads. In claim 3, of the instant application the phrase **for attachment in one of a conventional die attach to lead frame connect process and a LOC connect process** is added to the claim. However, a connector (i.e. bonding wire) is an attachment means for a conventional die to a lead frame. A rejection based on double patenting of the "same invention" type finds its support in the language of 35 U.S.C. 101, which states that "whoever invents or discovers any new and useful process ... may obtain a patent therefor ..." (Emphasis added). Thus, the term "same invention," in this context, means an invention drawn to identical subject matter. See *Miller v. Eagle Mfg. Co.*, 151 U.S. 186 (1894); *In re Ockert*, 245 F.2d 467, 114 USPQ 330 (CCPA 1957); and *In re Vogel*, 422 F.2d 438, 164 USPQ 619 (CCPA 1970).

A statutory type (35 U.S.C. 101) double patenting rejection can be overcome by canceling or amending the conflicting claims so they are no longer coextensive in scope. The filing of a terminal disclaimer cannot overcome a double patenting rejection based upon 35 U.S.C. 101.

4 Claims 1 and 3 are rejected under 35 U.S.C. 101 as claiming the same invention as that of claims 1 and 3 of prior U.S. Patent No. 6,316,824. This is a double patenting rejection.

### ***Double Patenting***

4. A rejection based on double patenting of the "same invention" type finds its support in the language of 35 U.S.C. 101, which states that "whoever invents or discovers any new and useful process ... may obtain a patent therefor ..." (Emphasis added). Thus, the term "same invention," in this context, means an invention drawn to identical subject matter. See *Miller v. Eagle Mfg. Co.*, 151 U.S. 186 (1894); *In re Ockert*, 245 F.2d 467, 114 USPQ 330 (CCPA 1957); and *In re Vogel*, 422 F.2d 438, 164 USPQ 619 (CCPA 1970).

A statutory type (35 U.S.C. 101) double patenting rejection can be overcome by canceling or amending the conflicting claims so they are no longer coextensive in scope. The filing of a terminal disclaimer cannot overcome a double patenting rejection based upon 35 U.S.C. 101.

5. Claims 1-20 are rejected under 35 U.S.C. 101 as claiming the same invention as that of claims 1 and 18 of prior U.S. Patent No. 6,507,109. This is a double patenting rejection.